

### **AMENDMENTS TO THE SPECIFICATION**

Please replace the paragraph beginning at page 2, line 12, with the following rewritten paragraph:

-- However, it was found that a-the melting point of a-the tin-bismuth alloy did not have a constant value in spite of the fact that a-content of the bismuth content in the alloy solder was always constant. --

Please replace the paragraph beginning at page 2, line 15, with the following rewritten paragraph:

-- A study was made to clear better understand the cause of this melting point fluctuation, and it was found that bismuth content is not uniform in the alloy deposit. That is, bismuth content tends to be higher near the surface of a tin-bismuth alloy deposit, which makes the melting point of the alloy different between near the surface and deep inside of the alloy deposit. This non-uniform bismuth content distribution in the alloy deposit not only changes a melting point of the tin-bismuth alloy, but also may have an influence on the bonding properties of the leads having the alloy deposit thereon and lower a reliability of the film carrier tapes. --

Please replace the paragraph beginning at page 3, line 2, with the following rewritten paragraph:

-- A study was made to clear investigate the cause of the non-uniformity of bismuth content in a tin-bismuth alloy solder deposit, and the following fact was found. --

Please delete the section heading beginning at page 5, line 3.

Please replace the paragraph beginning at page 5, line 4, with the following rewritten paragraph:

-- It is an object of the invention to provide a film carrier tape for mounting electronic devices thereon, in which lead portions are provided with a tin-bismuth alloy deposit containing a substantially uniform distribution of bismuth uniformly. --

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Please replace the paragraph beginning at page 27, line 6, with the following rewritten paragraph:

-- The film carrier tape, the production method thereof, and the plating apparatus according to the invention will be described in detail by the following Examples. But it should be ~~construed~~understood that the invention is in no way limited to those Examples. --

Please replace the section heading beginning at page 27, line 11, with the following rewritten section heading:

{Example 1}

Please replace the section heading beginning at page 31, line 15, with the following rewritten section heading:

{Comparative Example 1}

Please replace the section heading beginning at page 32, line 3, with the following rewritten section heading:

{Examples 2-6 and Comparative Examples 2-3}